

REMARKS

Applicants respectfully request reconsideration of this application as amended. Claims 4-5, 7-8 and 14-15 have been amended to present the claims in better form for allowance and for possible consideration on appeal. Applicants respectfully request the Examiner to accept the proposed amendments. Claims 12 and 19-29 have been previously cancelled. New claims 30 and 31 have been added. Therefore, claims 1-11, 13-18 and 30-31 are now are presented for examination.

35 U.S.C. § 103 Rejection

Claims 1-5, 7, 11, 15 and 17 are rejected under 35 U.S.C. §103(a) as being unpatentable over Hsieh U.S. Patent No. 6,564,986 (“Hsieh”), in view of Stewart et al., U.S. Application No. 2003/0170450 (“Stewart”).

The Examiner is arguing against the original claims. The amended claims filed in the last Office Action response, mailed June 16, 2005, recite “determining parameters of a ball grid array (BGA) package having an array of solder balls; and applying a bonder to the parameters of the BGA package, wherein the bonder is applied independently of the array of solder balls, and the bonder is applied surrounding the array of solder balls.” (emphasis provided). The final Office Action, mailed August 8, 2005, does not address the amended claims. Applicants respectfully request the Examiner to carefully review the last Office Action response, and withdraw the final Office Action.

Hsieh discloses that the “BGA IC package is modified to link associated pairs of solder balls, e.g., *using wire bonding to form an upper portion of the daisy chain.* *Mounting the BGA IC package on the test PCB completes the daisy chain.* By alternating between the test PCB contact pads that are linked by conductive traces and the *solder*

balls that are linked by wire bonding, the daisy chain provides a conductive path that passes through all solder balls of the BGA IC package.” (Abstract).

Stewart discloses a “*solid or semi-solid thermoplastic adhesive adhered to a surface mount electronic device . . . [and is] applied to any available surface on the connecting substrate of the surface mounted electronic device.*” (Abstract).

In contrast, claim 1, in pertinent part, recites “applying a bonder to the parameters of the BGA package, wherein the bonder is applied independently of the array of solder balls, and the bonder is applied surrounding the array of solder balls.” (emphasis provided). Applicants respectfully submit that neither Hsieh nor Stewart, individually or combined, teach or reasonably suggest such a feature. The *daisy chain* of Hsieh is not the same as applying a bonder to the parameters of the BGA package such that the bonder is applied independently of the array of solder and surrounding the array of solder balls, as recited by claim 1. As with Hsieh, Stewart also does not teach or reasonably suggest applying the bonder to the parameter of the BGA package, and that the bonder is applied independently of the array of solder and surrounding the array of solder balls, as recited by claim 1, and as such, fails to disclose those limitations that are missing from Hsieh. Accordingly, Applicants respectfully request the withdrawal of the rejections of claim 1 and its dependent claims.

Claims 11 and 15 contain limitations similar to those of claims 1. Accordingly, Applicants respectfully request the withdrawal of the rejection of claims 11 and 15 and their dependent claims.

Claims 6, 8-10, 14 and 18 are rejected under 35 U.S.C. §103(a) as being unpatentable over (“Hsieh”), in view of (“Stewart”) and in further view of Austin, et al., U.S. Patent No. 6,284,173 (“Austin”).

Claims 6, 8-10, 14 and 18 depend from one of independent claims 1 or 11 and thus include the limitations of their base claim. Accordingly, Applicants respectfully request the withdrawal of the rejection of claims 6, 8-10, 14 and 18.

Claim 13 stands rejected under 35 U.S.C. §103(a) as being unpatentable over (“Hsieh”), in view of (“Stewart”) and in further view of Longgood, U.S. Patent No. 6,045,032 (“Longgood”).

Claim 13 depends from independent claim 11 and thus includes the limitations of its base claim. Accordingly, Applicants respectfully request the withdrawal of the rejection of claim 11.

New Claims

New claims 30 and 31 depend from independent claim 15. Accordingly, Applicants respectfully submit that claims 30 and 31 are distinguished over the cited references.

Conclusion

In light of the foregoing, reconsideration and allowance of the claims is hereby earnestly requested.

Invitation for a Telephone Interview

The Examiner is requested to call the undersigned at (303) 740-1980 if there remains any issue with allowance of the case.

Request for an Extension of Time

Applicants respectfully petition for an extension of time to respond to the outstanding Office Action pursuant to 37 C.F.R. § 1.136(a) should one be necessary. Please charge our Deposit Account No. 02-2666 to cover the necessary fee under 37 C.F.R. § 1.17(a) for such an extension.

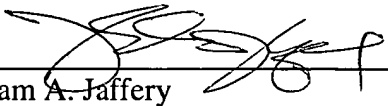
Charge our Deposit Account

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

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